

Description

The HSH8004 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

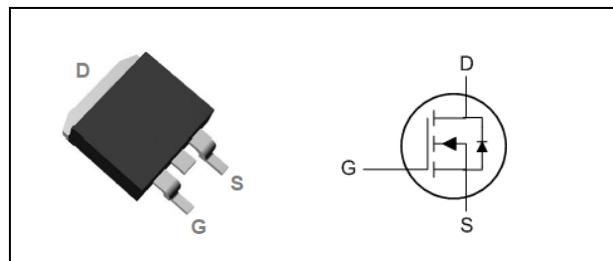
The HSH8004 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

Product Summary

V _{DS}	80	V
R _{DS(ON),TYP}	3.1	mΩ
I _D	175	A

TO-263 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	80	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	175	A
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	123	A
I _{DM}	Pulsed Drain Current ²	440	A
EAS	Single Pulse Avalanche Energy ³	378	mJ
P _D @T _C =25°C	Total Power Dissipation ⁴	192	W
T _{STG}	Storage Temperature Range	-55 to 175	°C
T _J	Operating Junction Temperature Range	-55 to 175	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	62	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	0.65	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$	80	---	---	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=20\text{A}$	---	3.1	3.5	$\text{m}\Omega$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=250\mu\text{A}$	1.2	1.8	2.5	V
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=80\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=25^\circ\text{C}$	---	---	1	μA
		$\text{V}_{\text{DS}}=64\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=25^\circ\text{C}$	---	---	100	
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$\text{V}_{\text{DS}}=5\text{V}$, $\text{I}_D=30\text{A}$	---	50	---	S
R_g	Gate Resistance	$\text{V}_{\text{DS}}=0\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	1.2	---	Ω
Q_g	Total Gate Charge (10V)	$\text{V}_{\text{DD}}=40\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=20\text{A}$	---	80	---	nC
Q_{gs}	Gate-Source Charge		---	15	---	
Q_{gd}	Gate-Drain Charge		---	16	---	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=40\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{R}_g=6\Omega$, $\text{I}_D=20\text{A}$	---	17	---	ns
T_r	Rise Time		---	32	---	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time		---	50	---	
T_f	Fall Time		---	18	---	
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=40\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	4450	---	pF
C_{oss}	Output Capacitance		---	800	---	
Crss	Reverse Transfer Capacitance		---	50	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,5}	$\text{V}_{\text{G}}=\text{V}_{\text{D}}=0\text{V}$, Force Current	---	---	175	A
V_{SD}	Diode Forward Voltage ²	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_s=\text{A}$, $\text{T}_J=25^\circ\text{C}$	---	---	1.5	V
t_{rr}	Reverse Recovery Time	$\text{I}_F=20\text{A}$, $d\text{I}/dt=100\text{A}/\mu\text{s}$, $\text{T}_J=25^\circ\text{C}$	---	40	---	nS
Q_{rr}	Reverse Recovery Charge		---	45	---	nC



Electrical Characteristic Diagrams

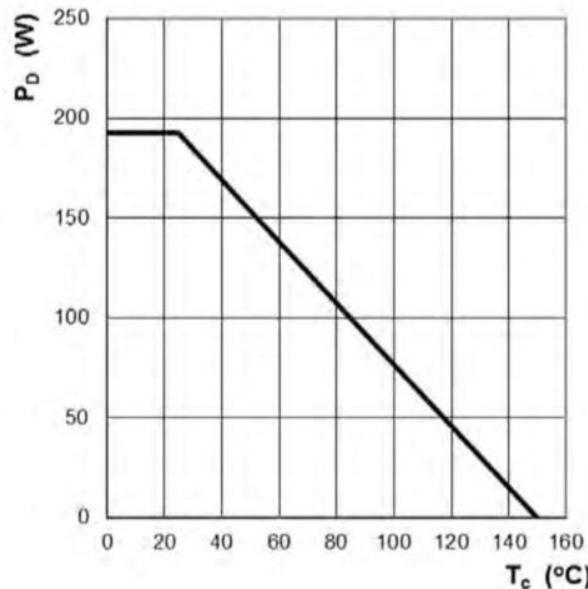


Figure 1: Power Dissipation

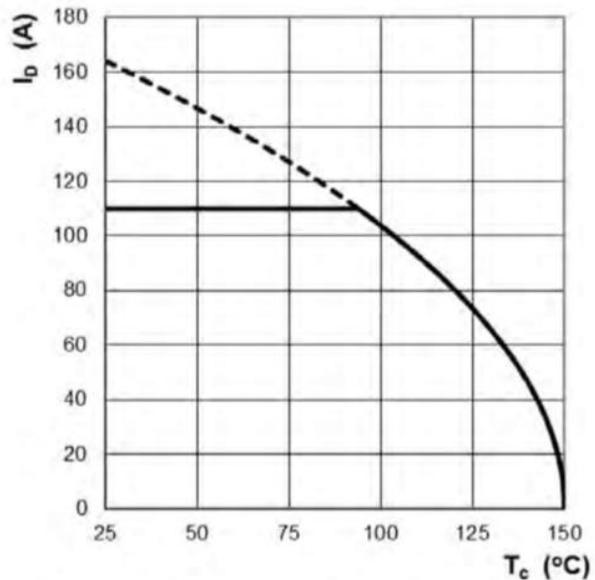


Figure 2: Continuous Drain Current vs. T_c

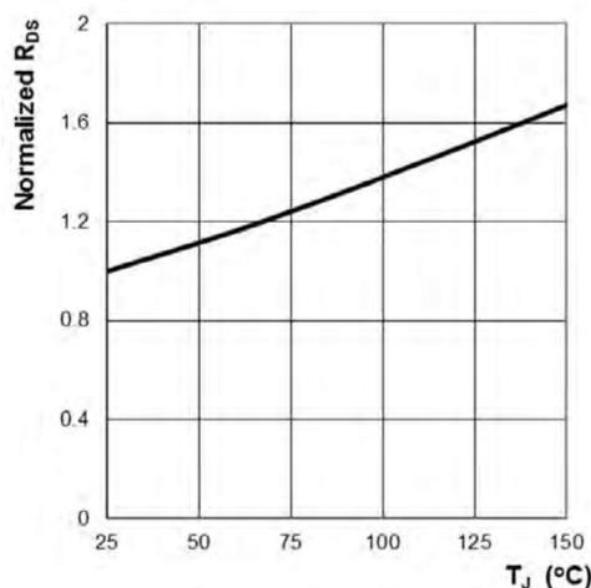


Figure 3: Normalized R_{D(on)} vs. T_j

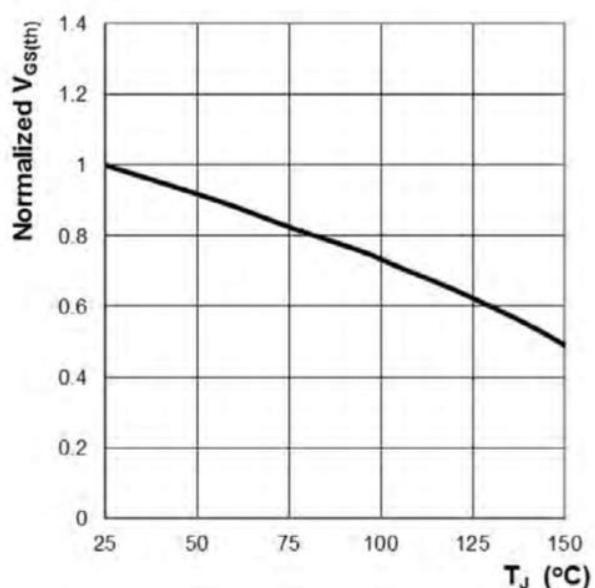


Figure 4: Normalized BV_{DSS} vs. T_j

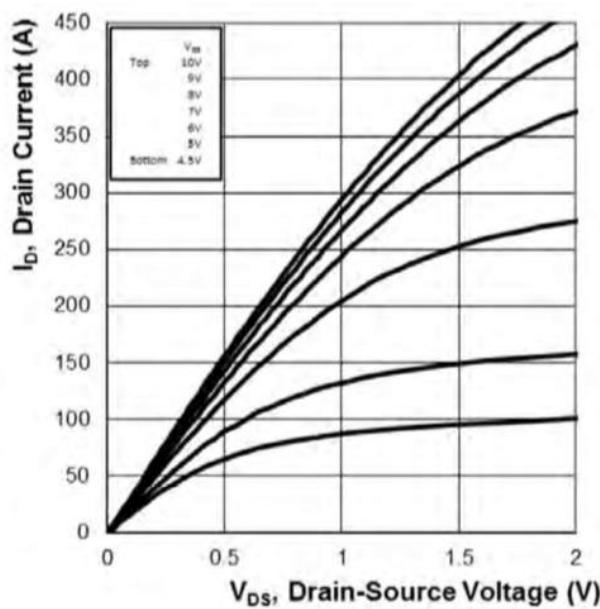


Figure 5: On-Region Characteristics

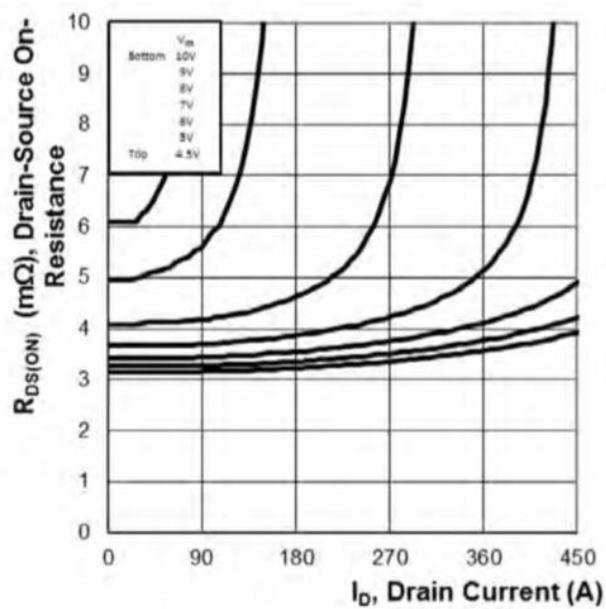


Figure 6: Typ. $R_{DS(on)}$ Variation vs. I_D and V_{GS}

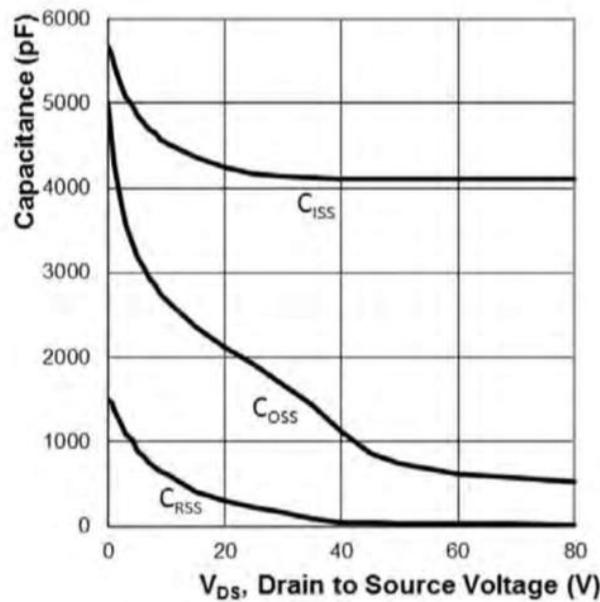


Figure 7: Typ. Capacitance Characteristics

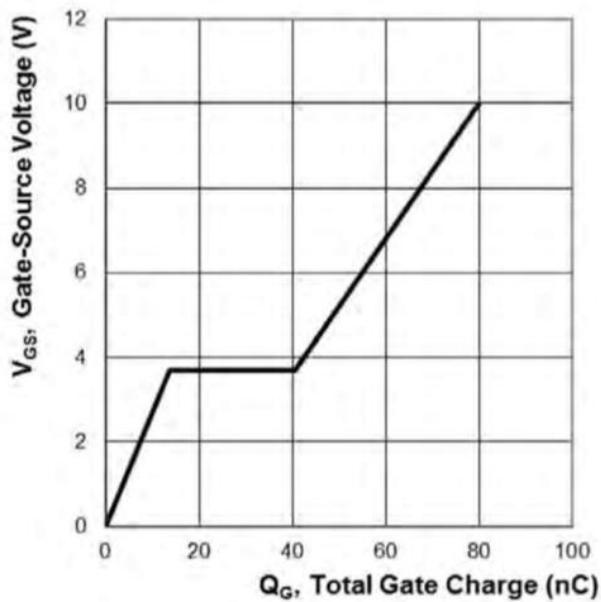


Figure 8: Typ. Gate Charge Characteristics

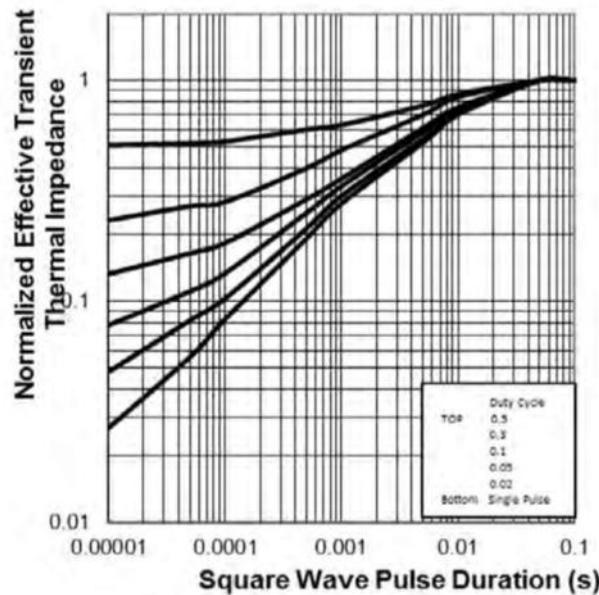


Figure 9: Normalized Thermal Transient Impedance, Junction-to-Case

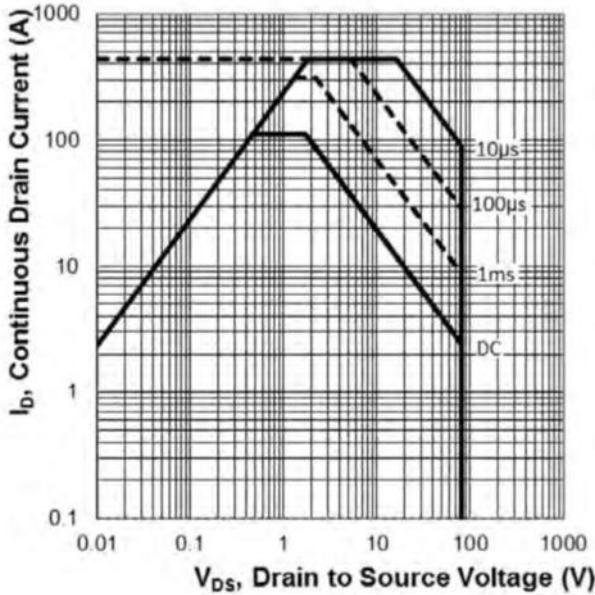


Figure 10: Maximum Safe Operation Area

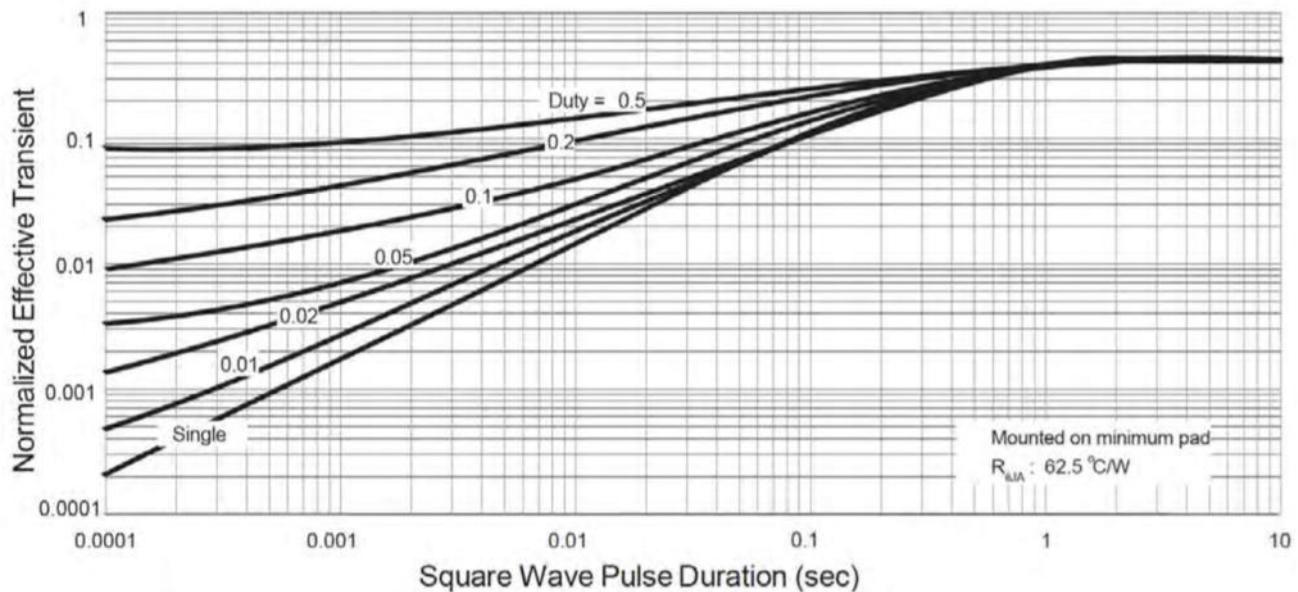


Fig 7 Normalized Maximum Transient Thermal Impedance



Parameter Test Circuits

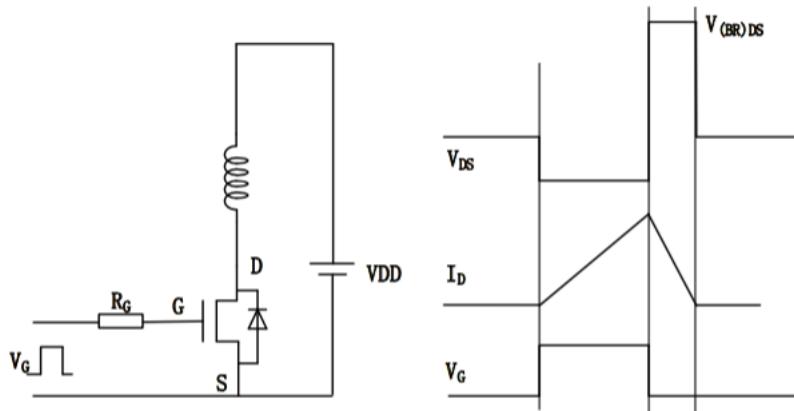


Figure 10 Unclamped Inductive Switching (UIS) Test circuit and waveforms

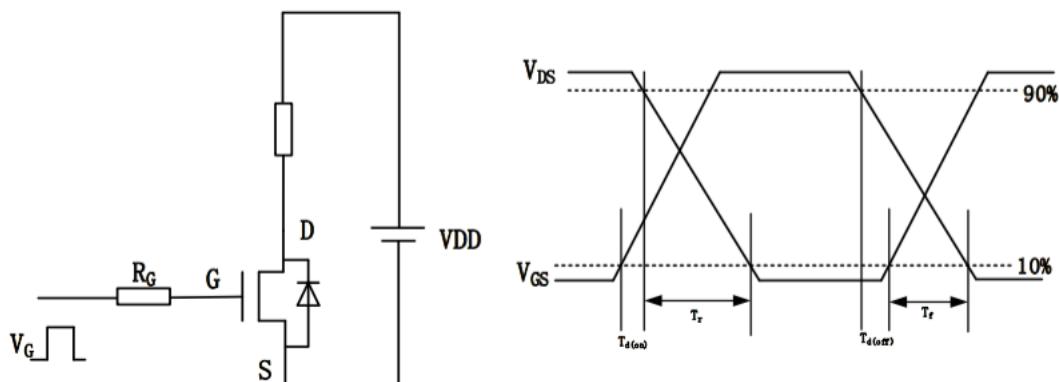


Figure 11 Resistive Switching time Test circuit and waveforms

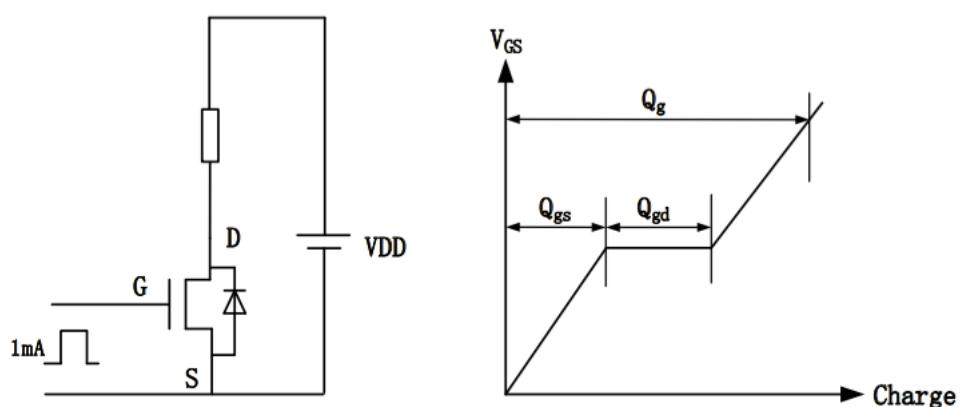


Figure 12 Gate charge Test circuit and waveforms